

APPROVED	O.G. FIG.	
BY	CLASS	SUBCLASS
DRAFTSMAN		

BEST AVAILABLE COPY

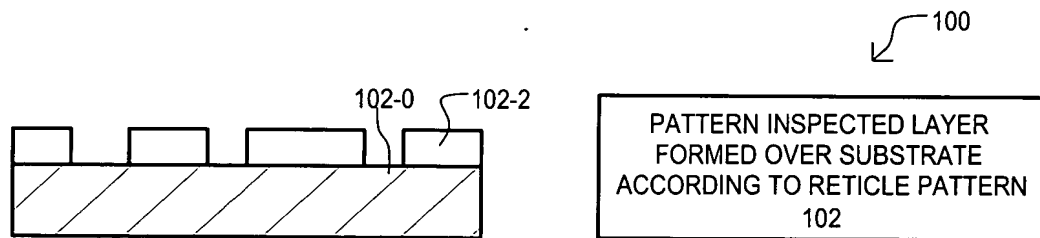


FIG. 1A

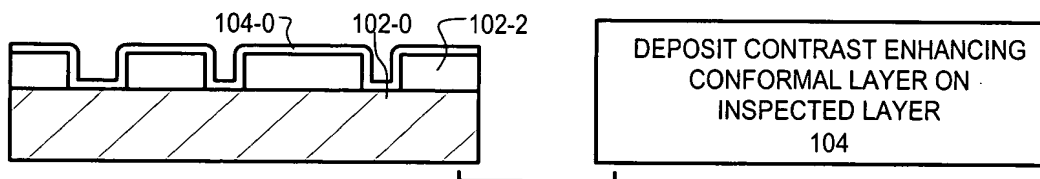


FIG. 1B

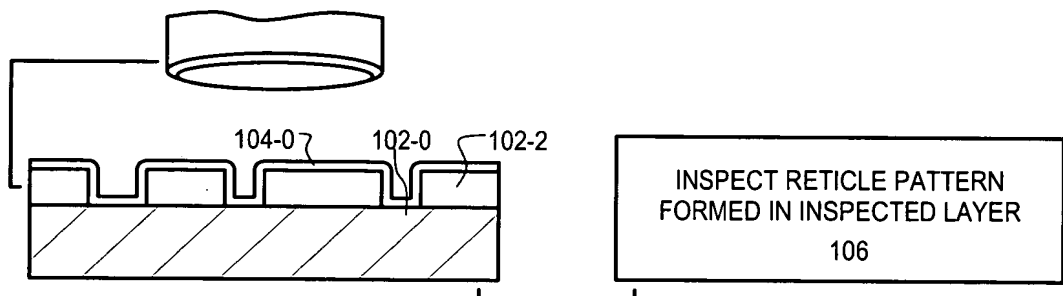


FIG. 1C

092034-07101

BEST AVAILABLE 200

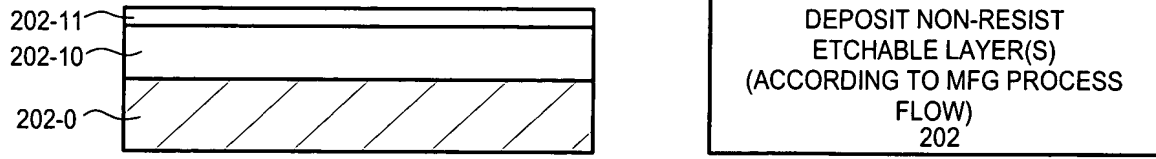


FIG. 2A

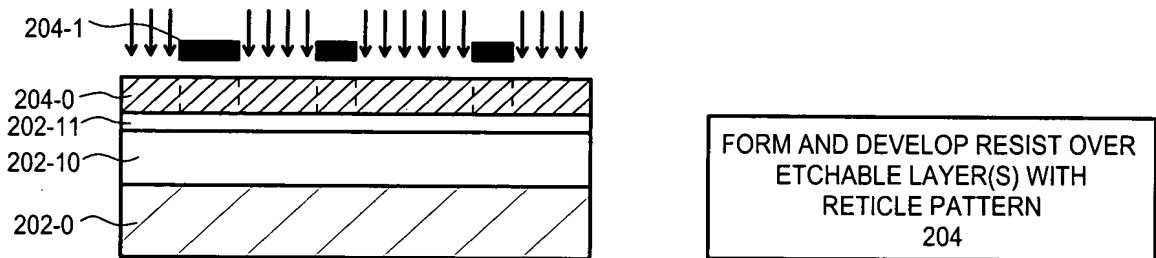


FIG. 2B

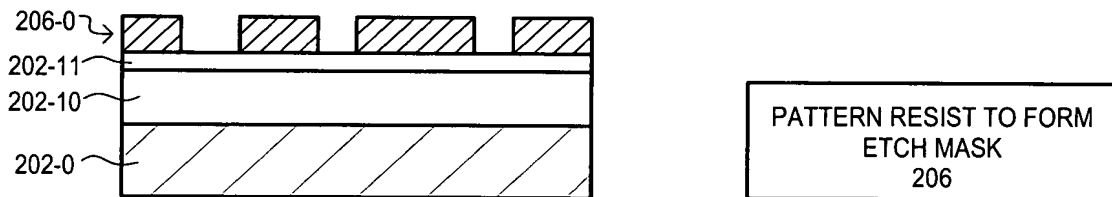


FIG. 2C

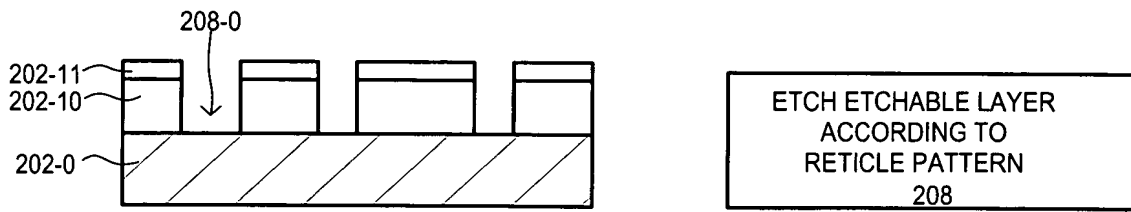


FIG. 2D

0920374-073101

APPROVED	O.G. FIG.	
BY	CLASS	SUBCLASS
DRAFTSMAN		

BEST AVAILABLE COPY

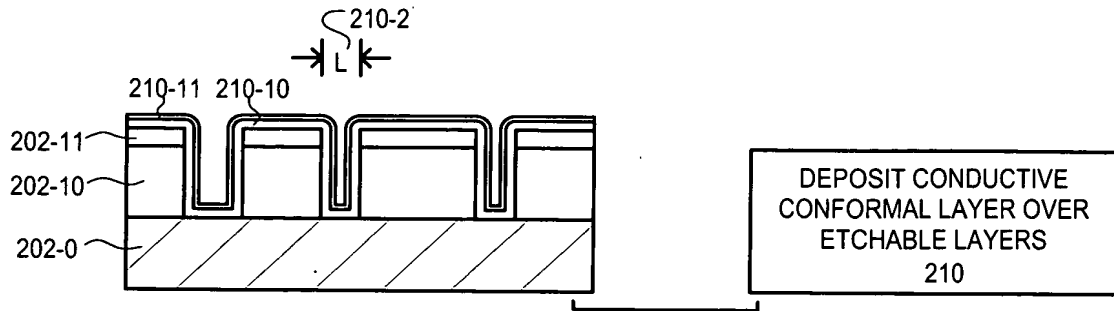


FIG. 2E

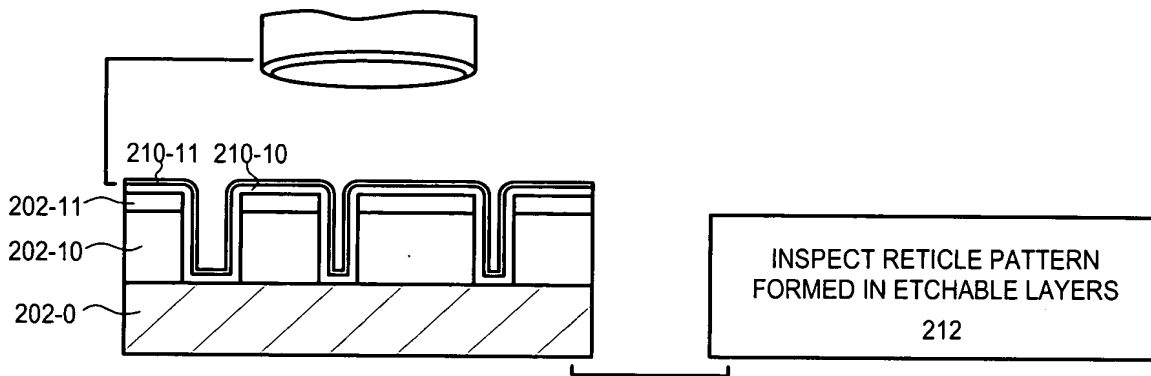
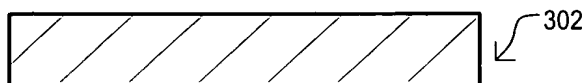


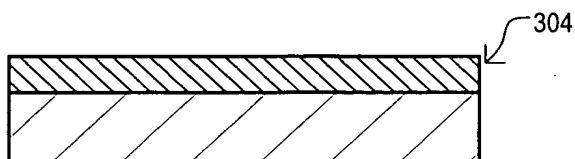
FIG. 2F

0920374.073101



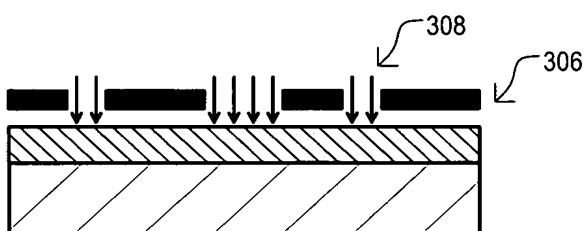
WAFER PREPARATION

FIG. 3A



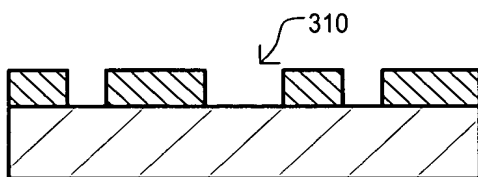
DEPOSIT RESIST

FIG. 3B



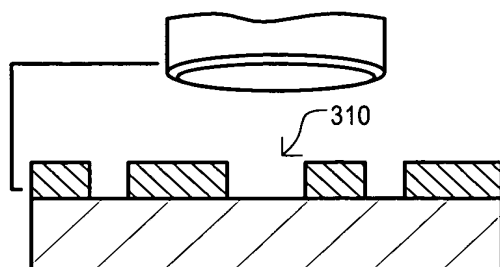
EXPOSE RESIST

FIG. 3C



DEVELOP RESIST

FIG. 3D



INSPECT RETICLE PATTERN
FORMED IN RESIST LAYER

FIG. 3E

SECRET